

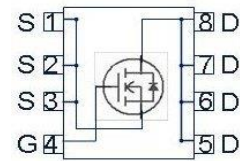
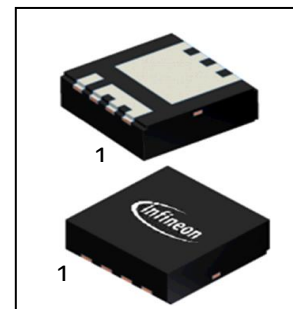
OptiMOS™ -5 Power-Transistor

Product Summary

| | | |
|------------------|-----|----|
| V_{DS} | 100 | V |
| $R_{DS(on),max}$ | 24 | mΩ |
| I_D | 30 | A |

Features

- OptiMOS™ - power MOSFET for automotive applications
- N-channel - Enhancement mode - Logic Level
- AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested
- Feasible for automatic optical inspection (AOI)

PG-TSDSON-8


| Type | Package | Marking |
|-----------------|-------------|---------|
| IAUZ30N10S5L240 | PG-TSDSON-8 | 5N1L240 |

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|--|----------------|---|--------------|------|
| Continuous drain current | I_D | $T_C=25\text{ °C}, V_{GS}=10\text{V}$ | 30 | A |
| | | $T_C=100\text{ °C}, V_{GS}=10\text{V}^{1)}$ | 22 | |
| Pulsed drain current ¹⁾ | $I_{D,pulse}$ | $T_C=25\text{ °C}$ | 120 | |
| Avalanche energy, single pulse ¹⁾ | E_{AS} | $I_D=12\text{A}$ | 17 | mJ |
| Avalanche current, single pulse | I_{AS} | - | 12 | A |
| Gate source voltage | V_{GS} | - | ±20 | V |
| Power dissipation | P_{tot} | $T_C=25\text{ °C}$ $T_J=175\text{ °C}$ | 45.5 | W |
| Operating and storage temperature | T_j, T_{stg} | - | -55 ... +175 | °C |
| IEC climatic category; DIN IEC 68-1 | - | - | 55/175/56 | - |

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|------------|--|--------|------|------|------|
| | | | min. | typ. | max. | |
| Thermal characteristics¹⁾ | | | | | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | - | 3.3 | K/W |
| Thermal resistance, junction - ambient | R_{thJA} | 6 cm ² cooling area ²⁾ | - | - | 62 | |

Electrical characteristics, at $T_j=25^\circ\text{C}$, unless otherwise specified

Static characteristics

| | | | | | | |
|----------------------------------|---------------|--|-----|------|-----|------------|
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=1mA$ | 100 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=15\mu A$ | 1.2 | 1.7 | 2.2 | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=100V, V_{GS}=0V, T_j=25^\circ\text{C}$ | - | - | 1 | μA |
| | | $V_{DS}=100V, V_{GS}=0V, T_j=125^\circ\text{C}^{1)}$ | - | - | 100 | |
| Gate-source leakage current | I_{GSS} | $V_{GS}=20V, V_{DS}=0V$ | - | - | 100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=4.5V, I_D=15A$ | - | 26 | 31 | m Ω |
| | | $V_{GS}=10V, I_D=15A$ | - | 19.5 | 24 | |
| Gate resistance ¹⁾ | R_G | | - | 1.5 | - | Ω |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics¹⁾

| | | | | | | |
|------------------------------|--------------|---|---|-----|------|----|
| Input capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=50V,$ $f=1MHz$ | - | 640 | 832 | pF |
| Output capacitance | C_{oss} | | - | 113 | 147 | |
| Reverse transfer capacitance | C_{rss} | | - | 7.9 | 11.8 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=50V, V_{GS}=10V,$ $I_D=30A, R_G=3.5\Omega$ | - | 2 | - | ns |
| Rise time | t_r | | - | 1 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 4.6 | - | |
| Fall time | t_f | | - | 3.4 | - | |

Gate Charge Characteristics¹⁾

| | | | | | | |
|-----------------------|---------------|--|---|-----|-----|----|
| Gate to source charge | Q_{gs} | $V_{DD}=50V, I_D=15A,$ $V_{GS}=0 \text{ to } 10V$ | - | 2.1 | 2.7 | nC |
| Gate to drain charge | Q_{gd} | | - | 1.9 | 2.9 | |
| Gate charge total | Q_g | | - | 9.5 | 14 | |
| Gate plateau voltage | $V_{plateau}$ | | - | 3.3 | - | V |

Reverse Diode

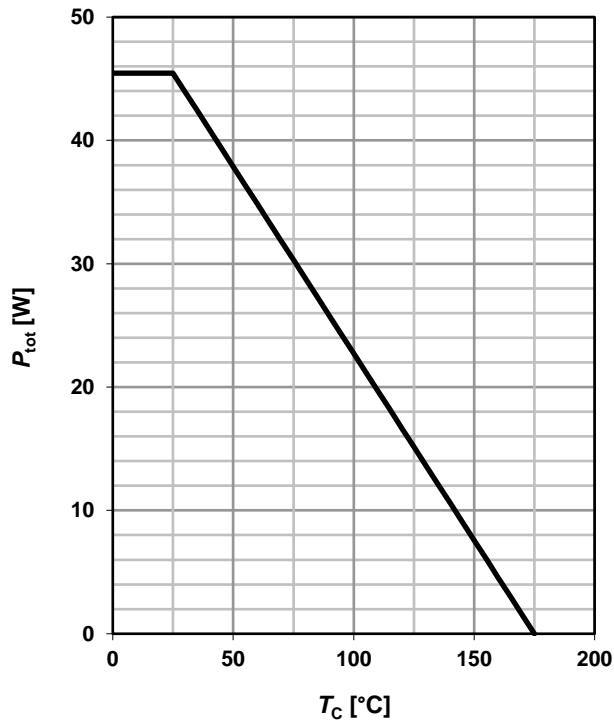
| | | | | | | |
|--|---------------|---|---|-----|-----|----|
| Diode continuous forward current ¹⁾ | I_S | $T_C=25^\circ C$ | - | - | 30 | A |
| Diode pulse current ¹⁾ | $I_{S,pulse}$ | | - | - | 120 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0V, I_F=15A,$ $T_j=25^\circ C$ | - | 0.9 | 1.1 | V |
| Reverse recovery time ¹⁾ | t_{rr} | $V_R=50V, I_F=30A,$ $di_F/dt=100A/\mu s$ | - | 37 | - | ns |
| Reverse recovery charge ¹⁾ | Q_{rr} | | - | 34 | - | nC |

¹⁾ Specified by design. Not subject to production test.

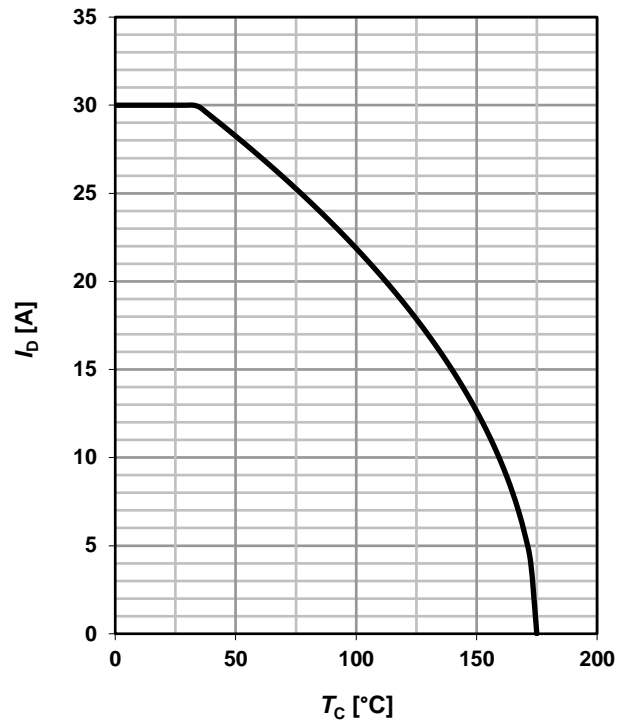
²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

1 Power dissipation

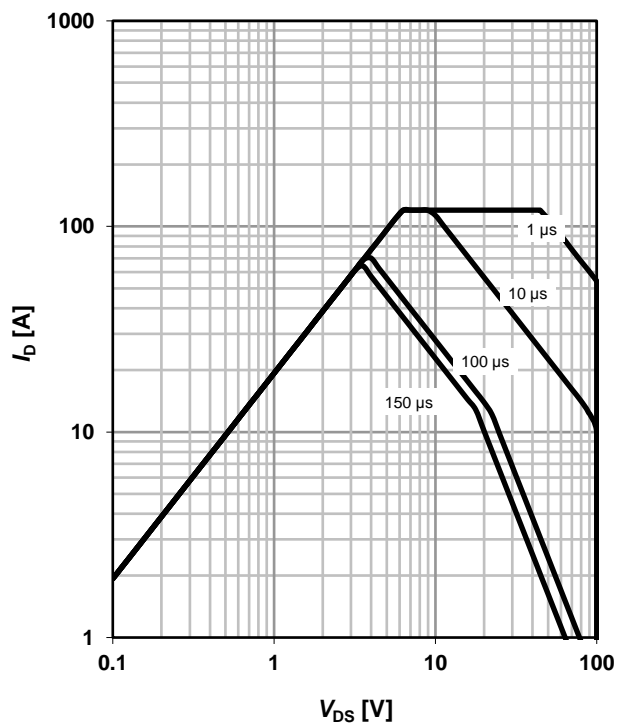
$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


2 Drain current

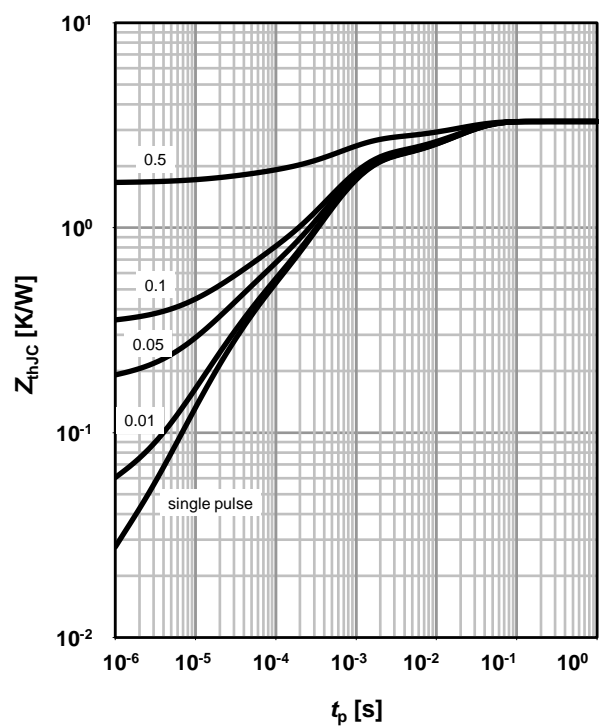
$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


3 Safe operating area

$$I_D = f(V_{\text{DS}}); T_C = 25 \text{ °C}; D = 0$$

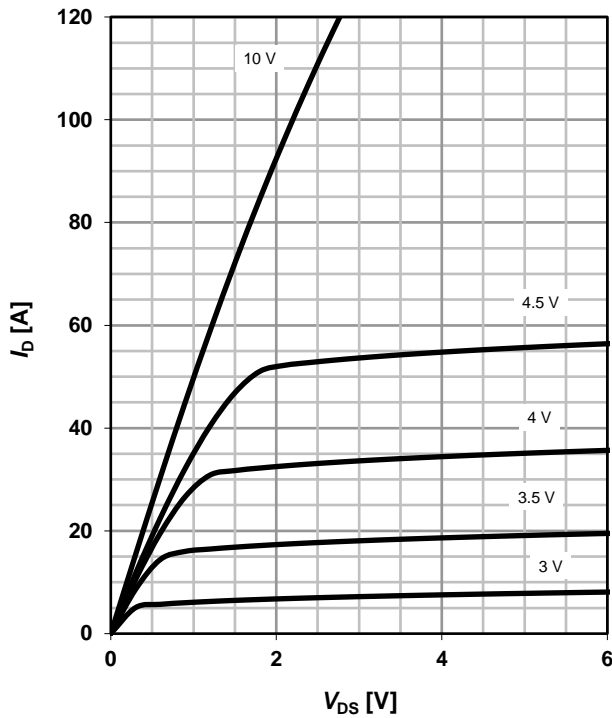
 parameter: t_p

4 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

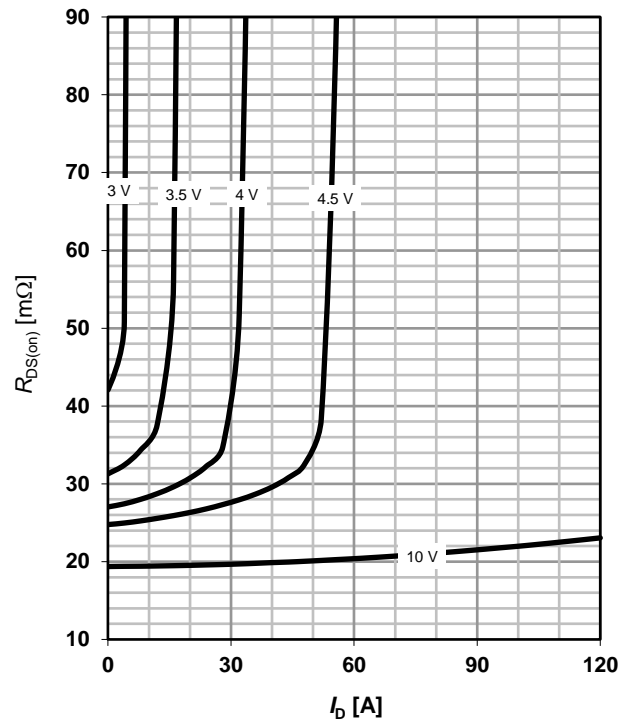
 parameter: $D = t_p/T$


5 Typ. output characteristics

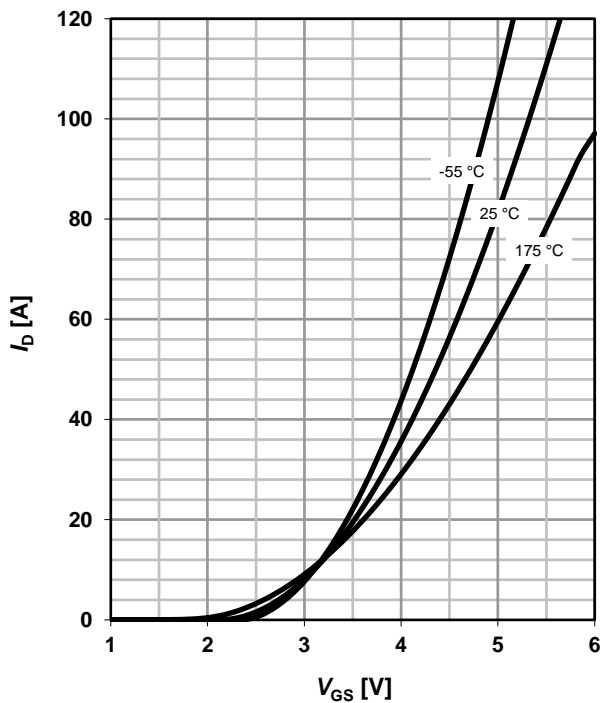
$$I_D = f(V_{DS}); T_j = 25\text{ °C}$$

 parameter: V_{GS}

6 Typ. drain-source on-state resistance

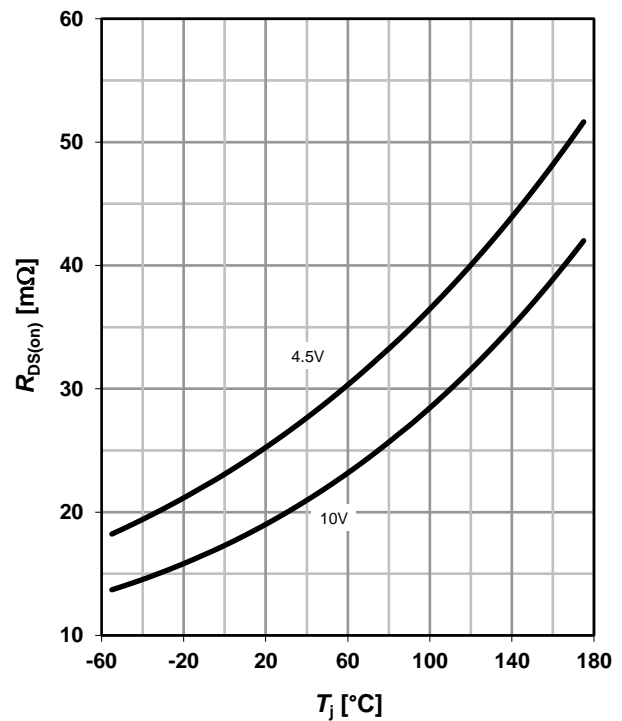
$$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$$

 parameter: V_{GS}

7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$$

 parameter: T_j

8 Typ. drain-source on-state resistance

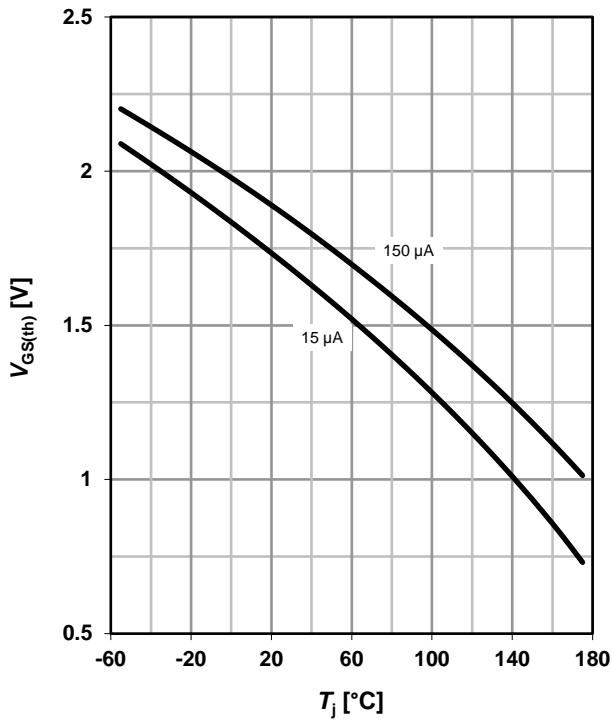
$$R_{DS(on)} = f(T_j); I_D = 15\text{ A}$$

 parameter: V_{GS}


9 Typ. gate threshold voltage

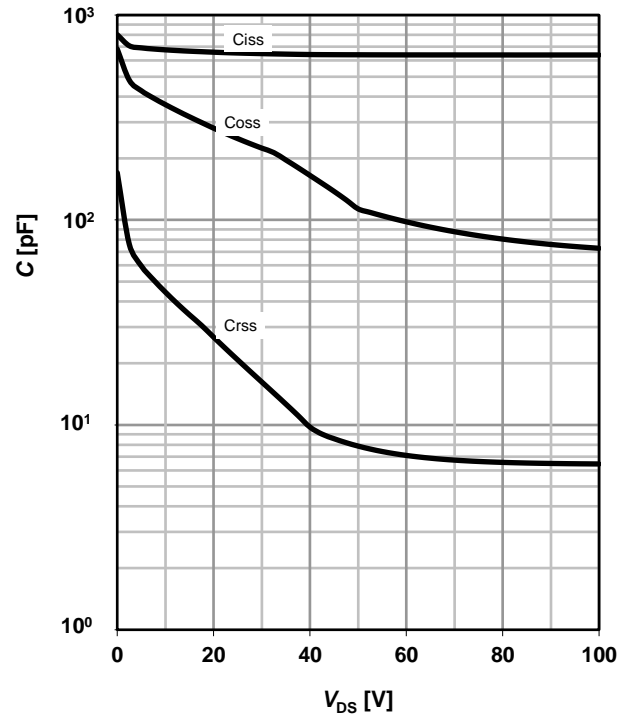
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

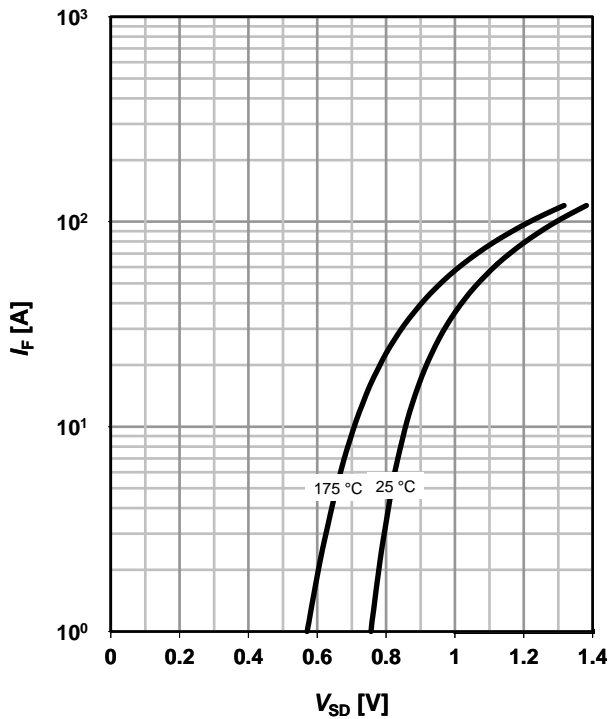
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



11 Typical forward diode characteristics

$I_F = f(V_{SD})$

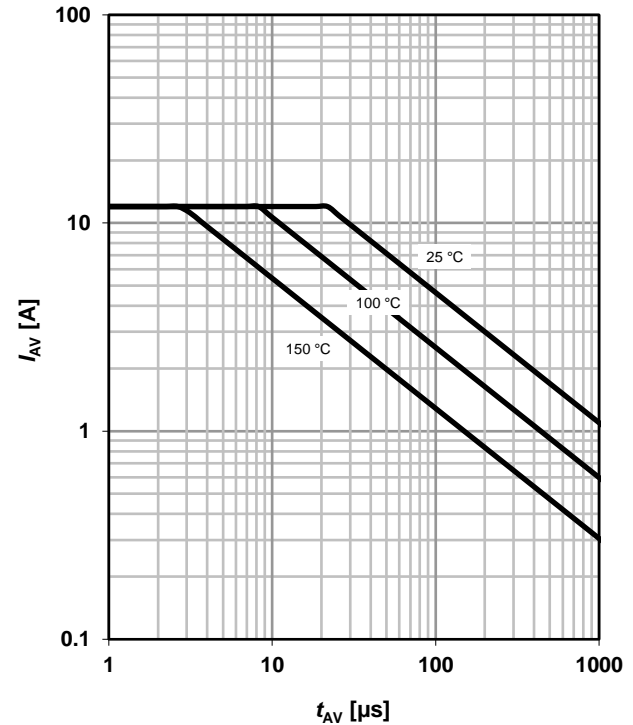
parameter: T_j



12 Avalanche characteristics

$I_{AS} = f(t_{AV})$

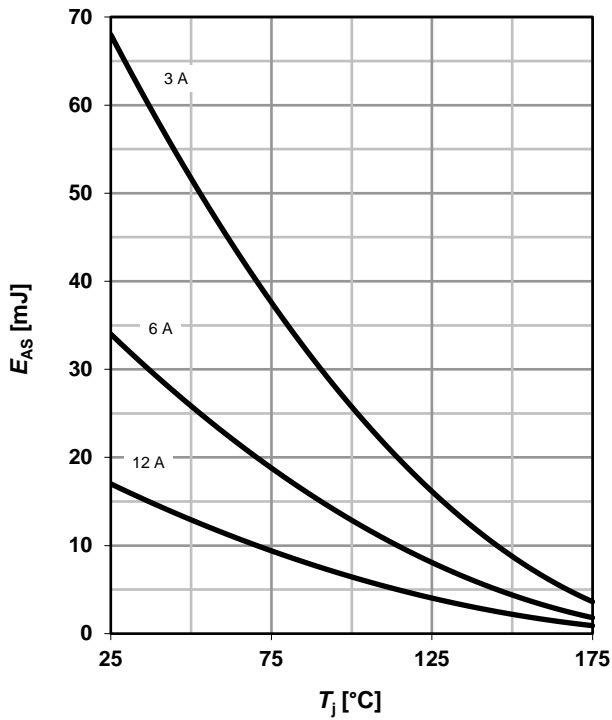
parameter: $T_{j(start)}$



13 Avalanche energy

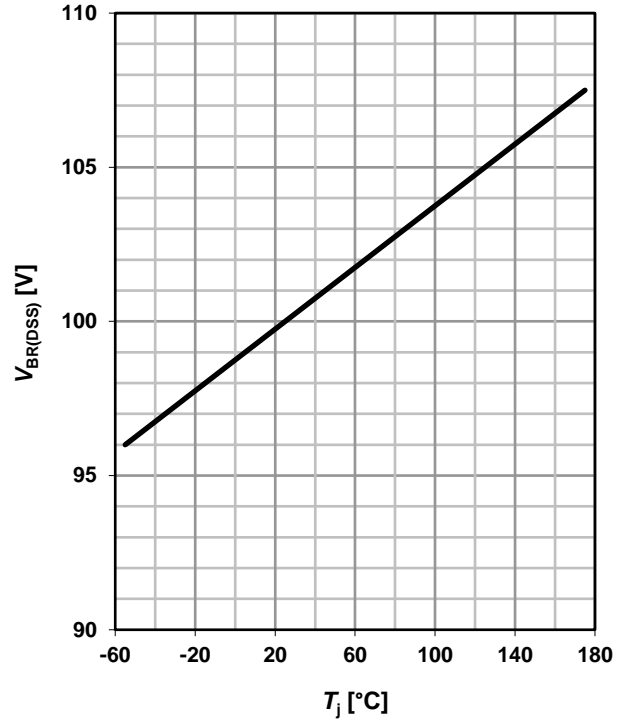
$$E_{AS} = f(T_j)$$

parameter: I_D



14 Drain-source breakdown voltage

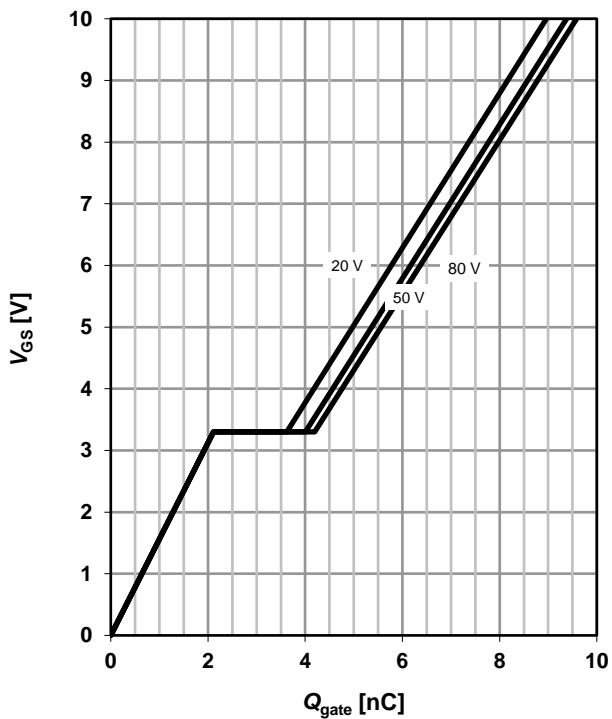
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



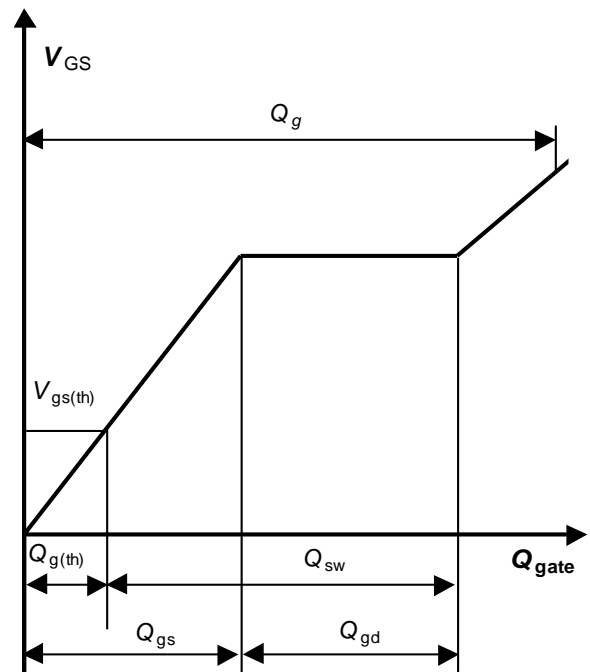
15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 15 \text{ A pulsed}$$

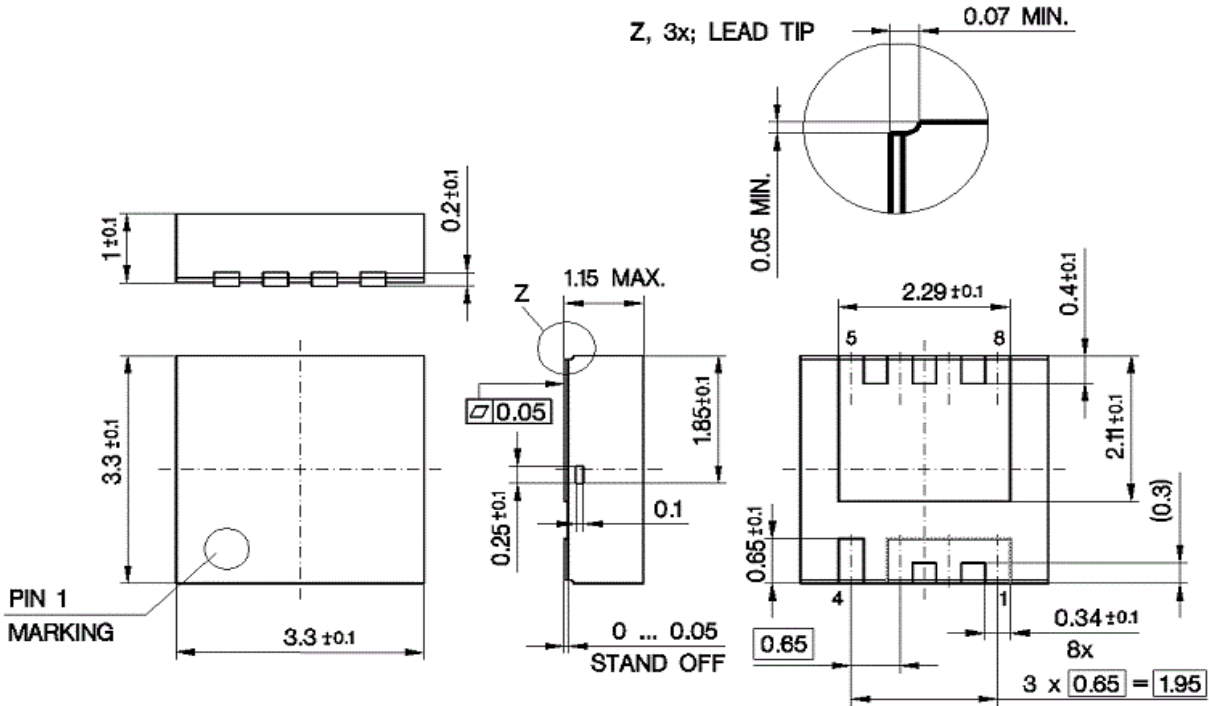
parameter: V_{DD}



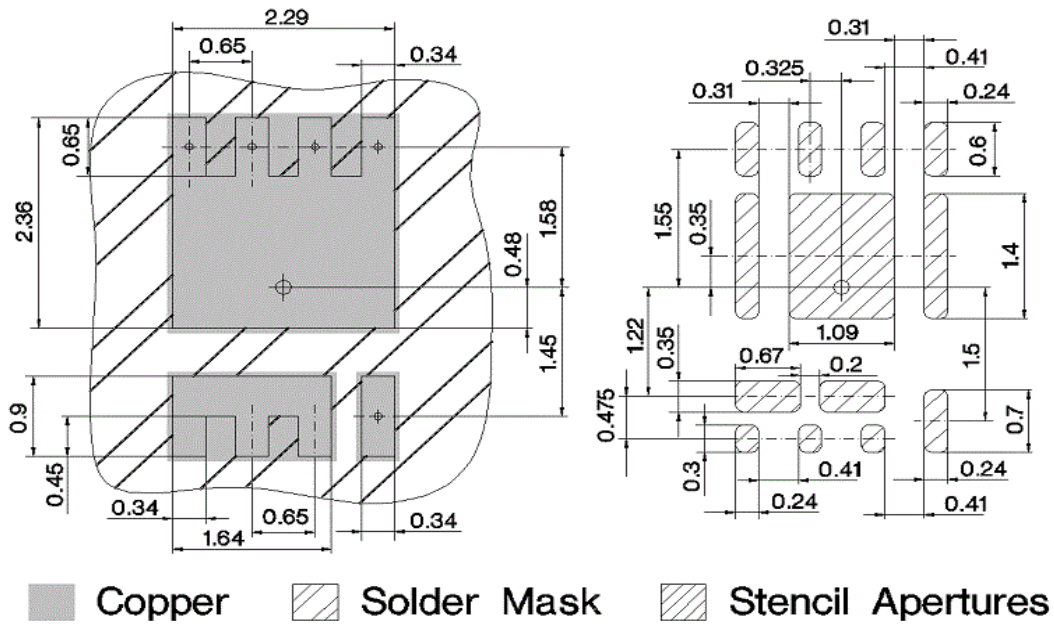
16 Gate charge waveforms



PG-TSDSON-8: Outline

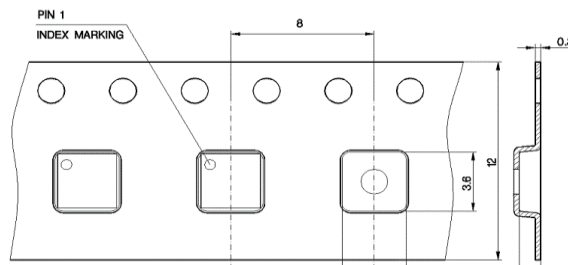


Footprint



Dimensions in mm

Packaging



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Revision History

| Version | Date | Changes |
|--------------|------------|------------------|
| Revision 1.0 | 23.07.2019 | Final Data Sheet |

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